

# ADS5294, 8-Channel, Analog-to-Digital Converter Evaluation Module

This user's guide gives a general overview of the evaluation module (EVM) and provides a general description of the features and functions to be considered while using this module. This manual is applicable to the ADS5294 analog-to-digital converters (ADC), which collectively are referred to as ADS529x. Use this document in combination with the respective ADC data sheet. The ADS529xEVM provides a platform for evaluating the ADC under various signal, clock, reference, and power supply conditions.

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## 1 Quick View of Evaluation Setup

Figure 1 shows an overview of the evaluation setup that includes the ADS5294EVM evaluation module (EVM), TSW1400EVM, external equipment, personal computer (PC), and software requirements.

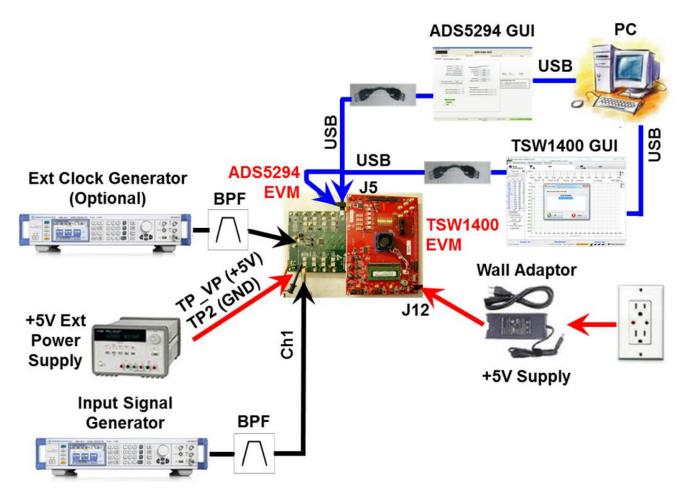


Figure 1. Evaluation Setup

**TSW1400EVM:** The high-speed LVDS deserializer board is required for capturing data from the ADS5294EVM and its analysis using the TSW1400 graphical user interface (GUI).

For more information pertaining to be TSW1400EVM, see: http://www.ti.com/tool/tsw1400evm.

**Equipment:** Signal generators (with low-phase noise) must be used as source of input signal and clock (optional) in order to get the desired performance. Additionally, band-pass filters (BPF) are required in signal and clock (optional) paths to attenuate the harmonics and noise from the generators.

**Power Supply:** A single +5-V supply powers the ADS5294EVM. The supplies for the ADS5294 device are derived from the +5-V supply. The power supply must be able to source up to 1.5 A. A +6-V supply can power the TSW1400EVM using a wall adapter.

**USB Interface to PC:** The USB connection from the ADS5294EVM and TSW1400EVM to the personal computer (PC) must be set up; Section 3.2 explains the USB driver installation.

ADS5294GUI: Section 3.1 explains the GUI installation procedure and its operation.



Default Configuration www.ti.com

## 2 Default Configuration



Figure 2. ADS5294EVM Basic Configuration

- 1. The ADS5294EVM basic configuration uses the onboard single-ended clock as the default option. See Section 9.2 for the ADC clock, various-mode jumper settings.
- 2. P1: +5-V Power supplies the connector.
- 3. JP4, JP5, and JP6 are set to enable +3.3V Analog, +1.8VD Digital, and +1.8VA Analog to device,



respectively.

- 4. JP13: Enable onboard CMOS clock.
- 5. JP16, JP18, JP19, JP20: ADC clock source selection jumpers.

#### 3 Software Installation and Operation

The ADS5294EVM comes with a software install. To Dowload the software, visit the ADS5294 product folder under *Tools & software* .

## 3.1 GUI Installation – Mandatory

Once the zip folder is downloaded, run setup.exe to install the software. The software to use the TSW1400EVM is called HSDCPro (High Speed Data Converter Pro). For information on how to download this software, please see Appendix A.

#### 3.2 USB Interface Driver Installation

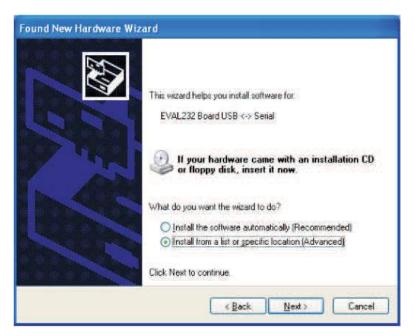
- Connect the USB port of EVM to your PC.
- If the driver has not been installed, then the message Window Found New Hardware appears. The
  Wizard as shown in the following illustration launches. Otherwise, skip Section 3.2 and go to Section 4.
- Select No, not this time from the options. Press Next button



• Select *Install from a list or specific location (Advanced)* as shown in the following illustration, and then click *Next*.



Test Setup www.ti.com



- Select Search for the best driver in these locations, and enter the file path for (C:\Program Files\Texas Instruments\ADS 5294EVM\CDM 2.04.06 WHQL Certified) in the combo-box. or browse to it by clicking the browse button. Once the file path has been entered in the box, click Next to proceed.
- If Windows<sup>™</sup> XP is configured to warn when unsigned (non-WHQL certified) drivers are about to be installed, the following screen is displayed unless installing a Microsoft<sup>™</sup> WHQL-certified Driver. Click on *Continue Anyway* to continue with the installation. If Windows XP is configured to ignore file signature warnings, no message appears.



#### 4 Test Setup

To evaluate the ADS5294 device, a TSW1400EVM is required. Figure 3 shows the exact setup of these two boards and external connectors.

- Connect +5-V supply at P1 connector or across TP VP (+5V) and TP2 (GND).
- Connect USB cable from PC to USB1 on ADS5294EVM.
- Connect ADS5294EVM to TSW1400EVM using P10 connector.
- Connect USB cable from PC to USB port J8 of TSW1400EVM.
- Connect +6-V wall adapter to TSW1400EVM at J7 connector.



www.ti.com Power Up ADS5294

For the default configuration as shown in Figure 2, it is unnecessary to have an external sampling clock. The onboard CMOS clock oscillator is used.

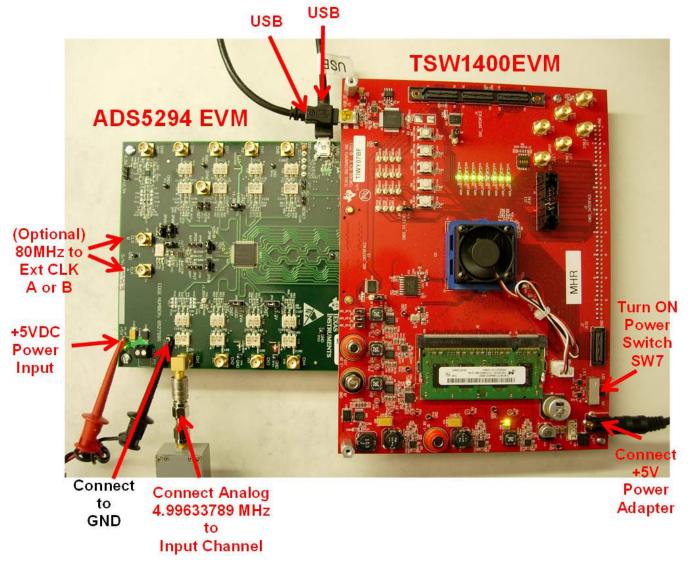


Figure 3. HW Setup With Connection Between TSW1400EVM and ADS5294EVM

## 5 Power Up ADS5294

After connecting the ADS5294EVM to the TSW1400 using the **P10** connector, +6-V adapter to TSW1400EVM, and +5 V (from the external power supply) to **P1** connector, then power up is complete. Three green LEDs and one orange LED turned on as shown in Figure 4 (also see Figure 13).



Launch ADS5294 GUI www.ti.com

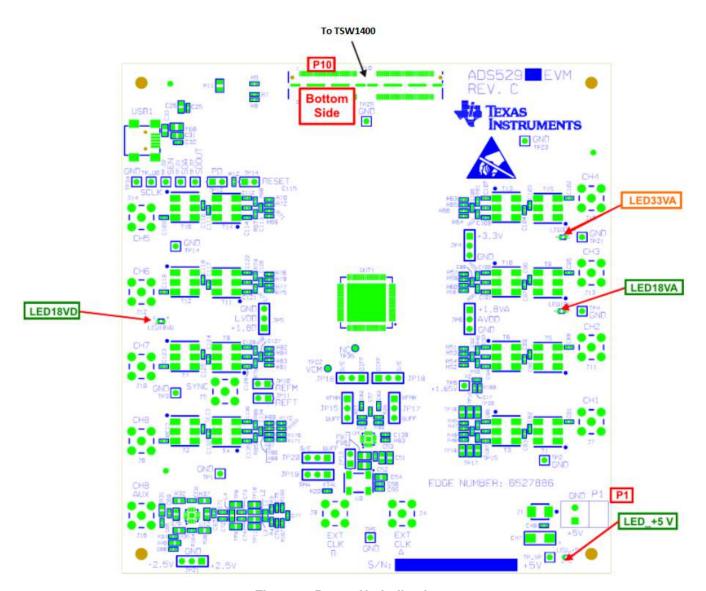


Figure 4. Power-Up Indications

## 6 Launch ADS5294 GUI

After launching the ADS5294 GUI, the GUI appears as is shown in Figure 5. After the GUI is completely launched, the window appears as is displayed in Figure 5. Select the **Top Level** tab to observe the default condition. The bottom status bar indicates *Ready for new command* and green (highlighted). Click on checkbox **PD**, and select it for power down to ensure proper software link to the hardware by observing change in current reading (approximately 450 mA to 150 mA) of the external +5-V power supply. For the rest of the test, **PD** must be unchecked. Click on **Soft Reset** button to reset device internally.



www.ti.com Launch ADS5294 GUI

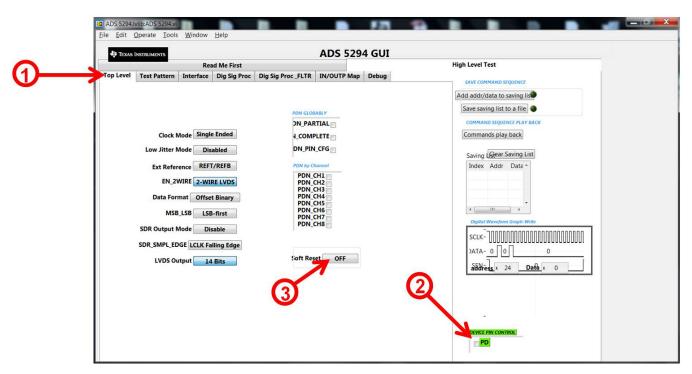
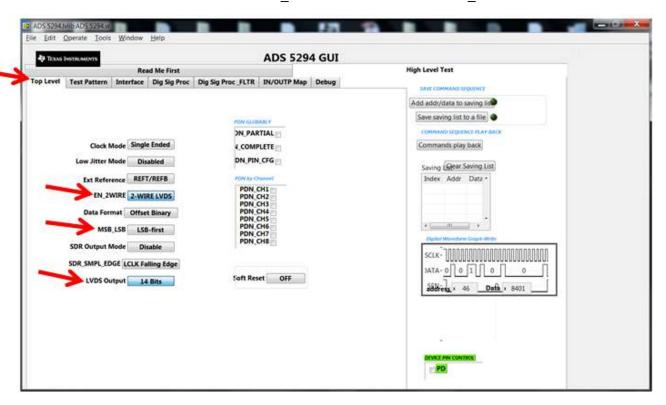


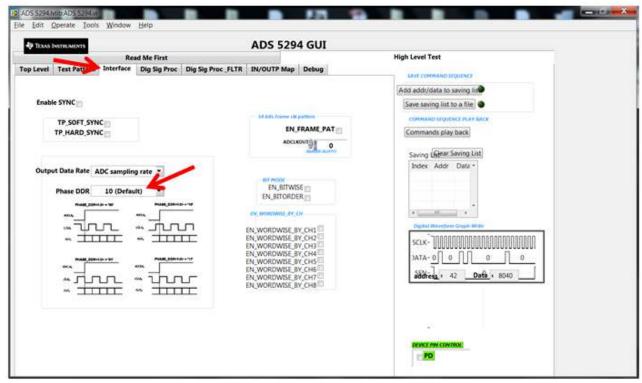
Figure 5. ADS5294 GUI Launch



Launch ADS5294 GUI www.ti.com

After GUI launch and verification of software communication with EVM, click on button **EN\_2WIRE**. This configures the ADC output interface in **2-WIRE LVDS** mode. Also click button **ADC Bit Resolution** to set ADC in **14 Bits** mode. Ensure that the **MSB LSB** button status shows **LSB First**.







www.ti.com Launch TSW1400 GUI

#### 7 Launch TSW1400 GUI

Launch TSW1400 GUI. The **Message** window displays this message to indicate that the setup of the TSW1400EVM and ADS5294EVM is working properly. If a different message or an error message appears, contact TI FAE.

- 1. Select ADS5294\_2W, 14bits, from the GUI.
- 2. **ADC Sampling Rate (Fs)** is fixed at 80 MHz; this is the onboard CMOS clock frequency.
- 3. **ADC Input Frequency** enter 5M and the GUI calculates the real coherent frequency (Fc) to 4.99633789M.

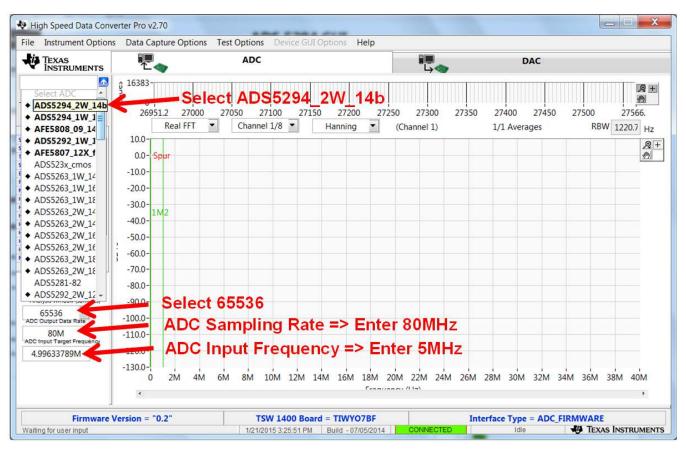


Figure 6. TSW1400 GUI Launch



TEST ADS5294 www.ti.com

#### 8 TEST ADS5294

#### Step 1: Time Domain

Select Time Domain page from TSW1400 GUI.

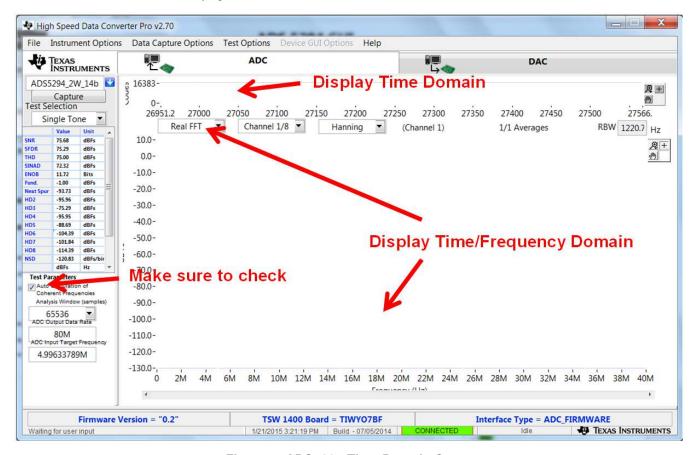


Figure 7. ADS5294 Time Domain Setup



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From ADS5294 GUI, go to Test Pattern page, then select RAMP PATTERN.

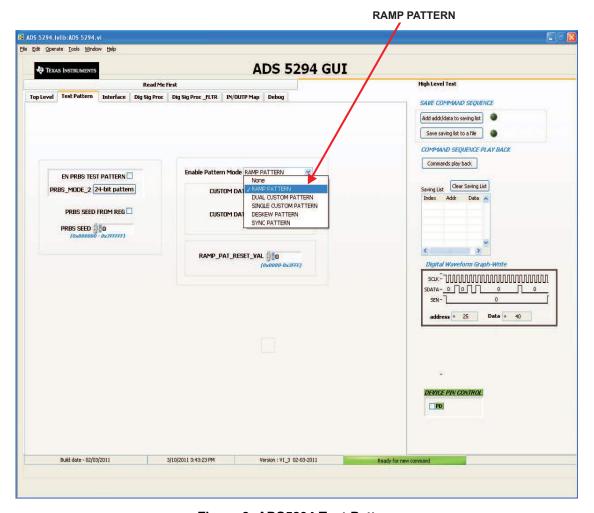


Figure 8. ADS5294 Test Pattern

- Press Capture button on TSW1400 GUI. You observe a ramping waveform on the TSW1400 GUI display area as shown in Figure 9.
- · Repeat for Channel 2...Channel 8.
- If each channel has the output as shown in the following illustration, you can proceed with the next step; otherwise, contact the TI FAE (Field Application Engineer) to troubleshoot the problem.
- On the ADS5294 GUI, change Test Pattern to None from RAMP PATTERN for next step.



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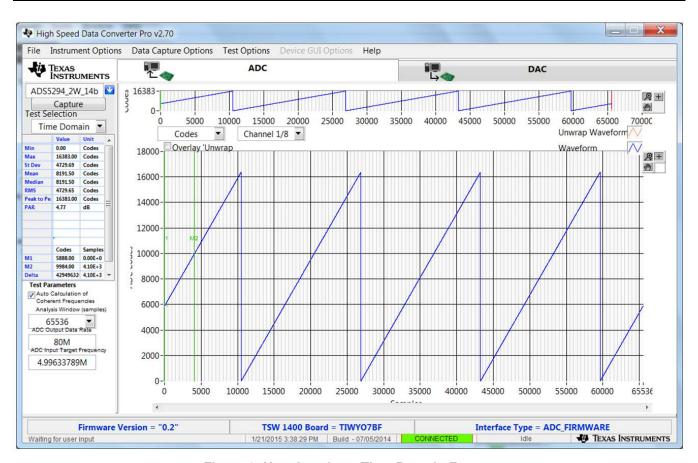
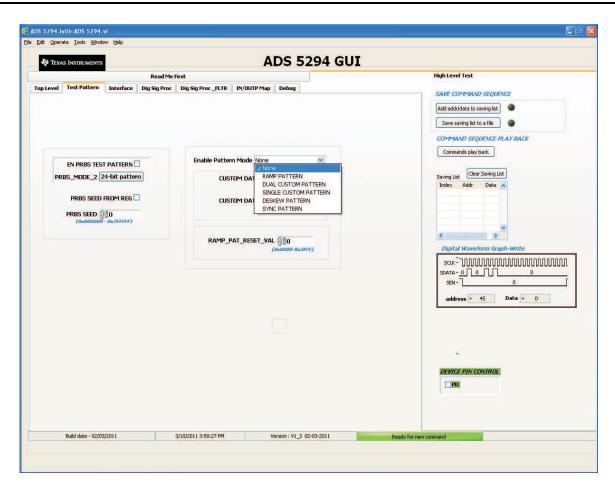


Figure 9. User Interface: Time Domain Format



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## 8.1 Step 2: Single Tone FFT

- Select Single Tone FFT page at TSW1400 GUI.
- Connect Channel 1 of ADS5294EVM to a signal generator through a BP filter. If no BP filter is presented, the result is not good.
- Set Amplitude of the signal generator to 10dBm
- Set Frequency of the signal generator to 4.99633789M to match the GUI.
- Change window option to Hanning. This is due to the fact that input signal and onboard CMOS clock are noncoherent.
- Press Capture button to get the test result.
- Repeat for Channel 2...Channel 8.



TEST ADS5294 www.ti.com

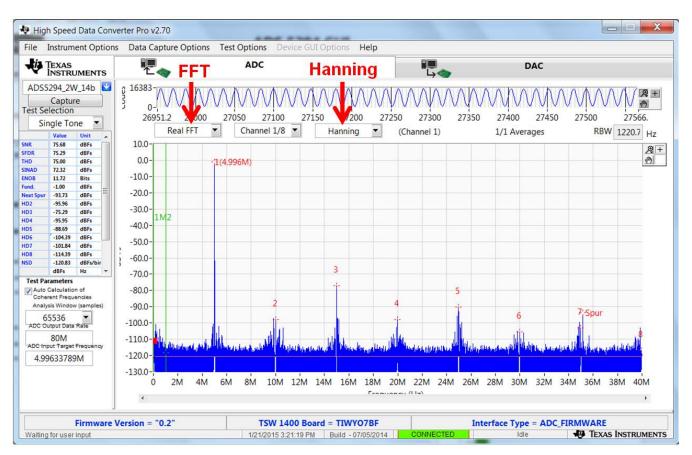


Figure 10. User Interface: Single FFT Format



www.ti.com Board Configuration

## 9 Board Configuration

## 9.1 Input/Output, Power Supply, and USB

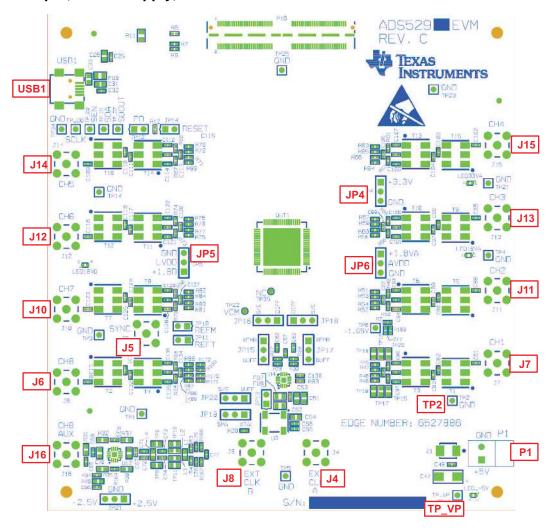


Figure 11. I/O, PWR, and USB Connector

Table 1. Input/Output, Power, and USB

| Connector   | Description  |
|---|--|
| J6,J7,J10J15  | Analog Input signals for Ch1-Ch8. Connect to a signal generator. A band-pass filter must be applied between the generator and the SMA to get a better result. (See Figure 3) |
| J16   | It is an alternative input for channel 8. Need to install two resistors (R169 and R170) and remove two resistors(R171 and R172) from J6.                                     |
| P1/TP_VP  | P1 is the +5-V power supply connector. TP_VP is the test point for +5-V power supply.  |
| JP4   | Onboard 3.3-V Analog enables. Set up as Figure 2 is a must to use onboard 3.3 V  |
| JP5   | Onboard 1.8-V Digital enables. Set up as Figure 2 is a must to use onboard 1.8 V   |
| JP6   | Onboard 1.8-V Analog enables. Set up as Figure 2 is a must to use onboard 1.8 V  |
| TP1, TP2, TP3,<br>TP4, TP5, TP14,<br>TP21, TP23,<br>TP25, TP34, | Ground test points.  |
| USB1  | USB interface connector  |



Board Configuration www.ti.com

# **Table 2. Channel 8 Configuration**

| Input Interface Type            | Connector | Description  |
|---------------------------------|-----------|--|
| Through Transformer (Default)   | J6        | In default configuration, R171 and R172 are already populated  |
| Through Amplifier (Not Default) | J16       | It is an alternative input for channel 8. Need to install two resistors (R169 and R170) and remove two resistors(R171 and R172) from J6.It uses TI THS4509 single-ended to differential amplifier. |



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#### 9.2 ADC Clock

Five options are available for the source of the ADC clocks. Refer to Table 3 for details. In Figure 12, ADS5294EVM uses an onboard, single-ended clock as the default option.

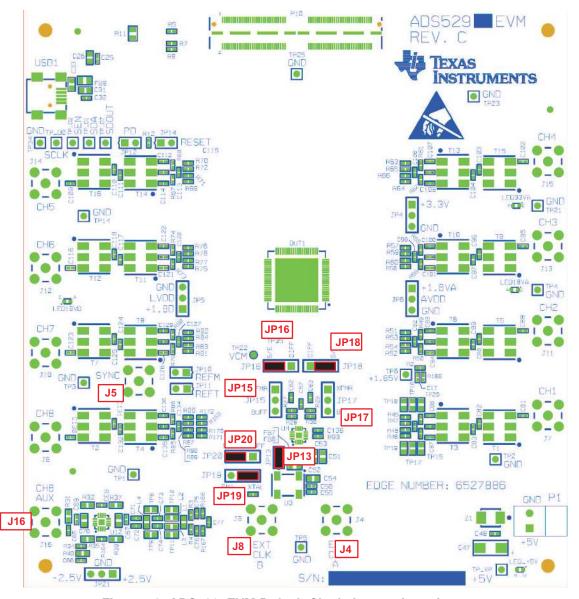


Figure 12. ADS5294EVM Default Clock Jumper Locations

**Table 3. ADC Clock Various Mode Jumper Settings** 

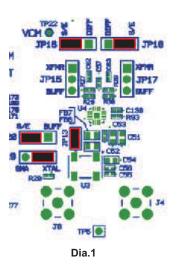
| Clock Type   |                                  | Reference<br>Designator         | Jumper Setting  | Diagram                    |
|--------------|----------------------------------|---------------------------------|---|----------------------------|
|              | Onboard CMOS<br>Oscillator       | JP13, JP19, JP20,<br>JP16, JP18 | JP13 (1-2), JP20 (2-3), JP19 (1-2), JP16 (2-3), JP18 (2-3)  | Dia. 1<br>(Default Option) |
| Single Ended | External CMOS<br>Clock Generator | J8, JP19, JP20, JP16,<br>JP18   | JP20 (2-3), JP19 (2-3), JP16 (2-3), JP18 (2-3) and Connect CMOS clock generator output at SMA connector J8. | Dia. 2                     |

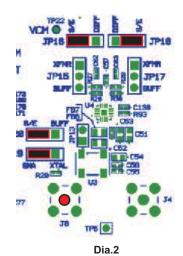


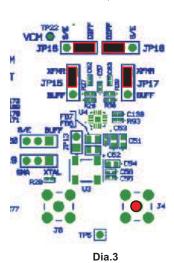
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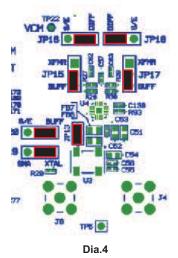
Table 3. ADC Clock Various Mode Jumper Settings (continued)

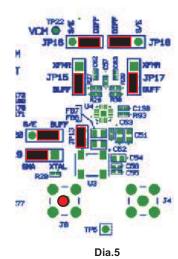
| Clock Type                   |  | Reference<br>Designator                        | Jumper Setting   |        |
|------------------------------|--|--|--|--------|
|                              | Transformer Based External                 | JP15, JP17, JP16,<br>JP18, J4                  | JP15 (1-2), JP16 (1-2), JP17 (1-2), JP18 (1-2),<br>and Connect external Clock source at SMA<br>connector J4  | Dia. 3 |
| Differential<br>Clock Signal | Onboard Clock<br>Buffer<br>(CDCLVP1102,U4) | JP13, JP19, JP20,<br>JP15, JP17, JP16,<br>JP18 | JP13 (1-2), JP20 (1-2), JP19 (1-2), JP15 (2-3), JP17 (2-3), JP16 (1-2), JP18 (1-2).  This configures the onboard CMOS oscillator as clock input to buffer. | Dia. 4 |
|                              |  | J8, JP19, JP20, JP15,<br>JP17, JP16, JP18      | JP19 (2-3), JP20 (1-2), JP15 (2-3), JP17 (2-3),<br>JP16 (1-2), JP18 (1-2) and Connect External<br>CMOS generator output at SMA connector J8.               | Dia. 5 |
|                              |  |  | This configures the external CMOS source as clock input to buffer.   |        |













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## 9.3 Light-Emitting Diodes

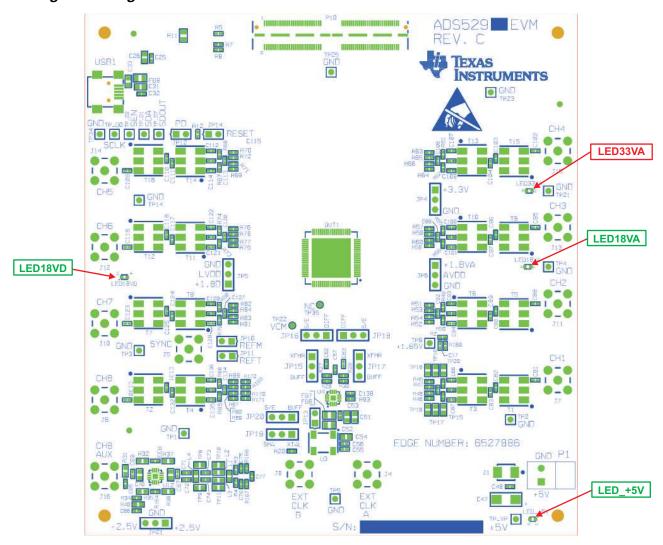


Figure 13. ADS5294EVM LED Location

**Table 4. LED Indicators** 

| Reference Designator | Power Supply | Color  |
|----------------------|--------------|--------|
| LED_+5V              | +5 V         | Green  |
| LED1.8VA             | +1.8 VA      | Green  |
| LED1.8VD             | +1.8 VD      | Green  |
| LED3.3VA             | +3.3 VA      | Orange |



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## 9.4 Miscellaneous Test Points

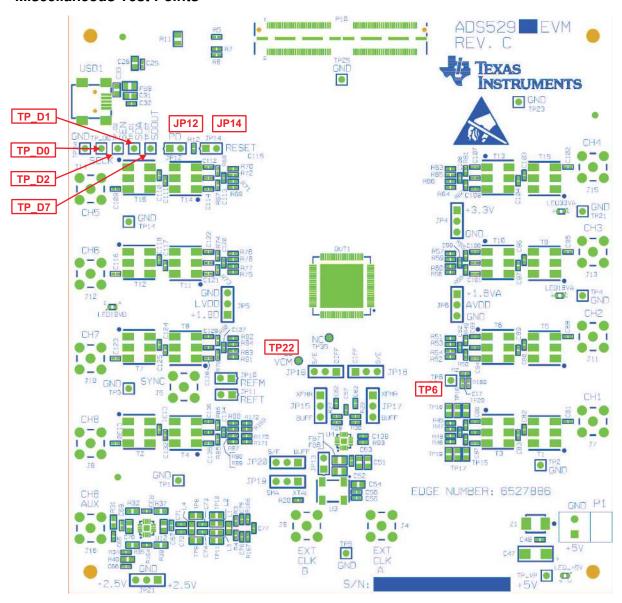


Figure 14. ADS5294EVM Test Point Locations

**Table 5. Miscellaneous Test Points** 

| Reference Designator | Description   |  |  |
|----------------------|---|--|--|
| TP22                 | VCM: Common-mode output pin, 0.95-V output              |  |  |
| TP6                  | CDC_VTH: Fixed voltage level (1.65 V)                   |  |  |
| TP_D0                | SCLK: Serial clock input                                |  |  |
| TP_D1                | SDA: Serial data input                                  |  |  |
| TP_D2                | TP_D2 SEN: Serial enable chip select                    |  |  |
| TP_D7                | SDOUT: Serial data output                               |  |  |
| JP14                 | JP14 RESET: Install to reset the device (DUT1) manually |  |  |
| JP12                 | PD: Install to power down the device (DUT1) manually    |  |  |



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#### 10 EVM Schematics

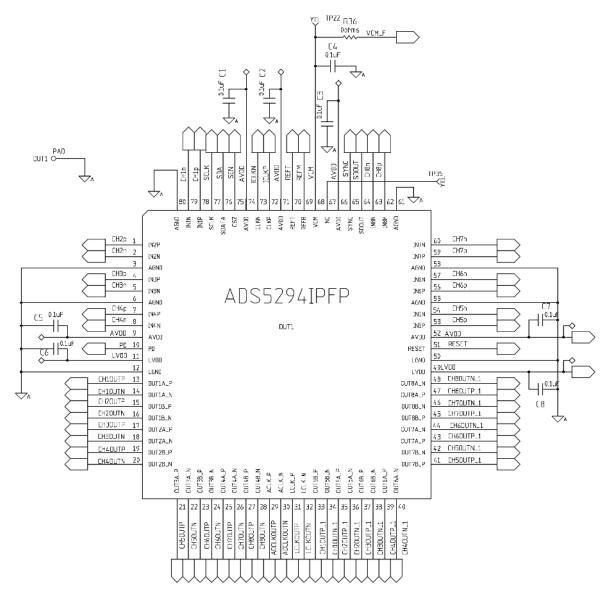


Figure 15. Schematic, Sheet 1 of 9



EVM Schematics www.ti.com

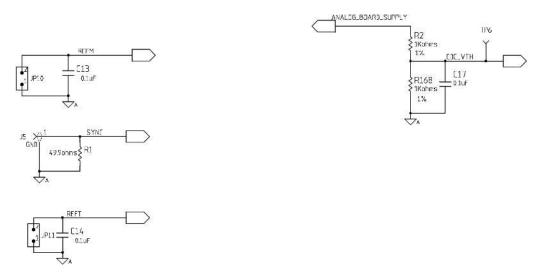


Figure 16. Schematic, Sheet 2 of 9

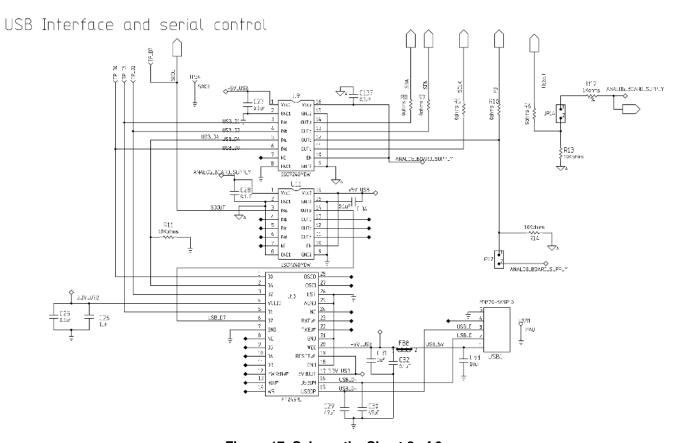
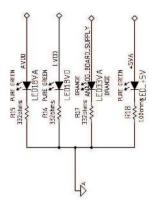


Figure 17. Schematic, Sheet 3 of 9



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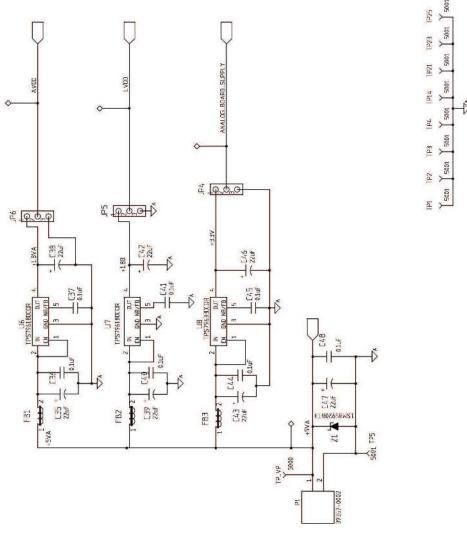


Figure 18. Schematic, Sheet 4 of 9



EVM Schematics www.ti.com

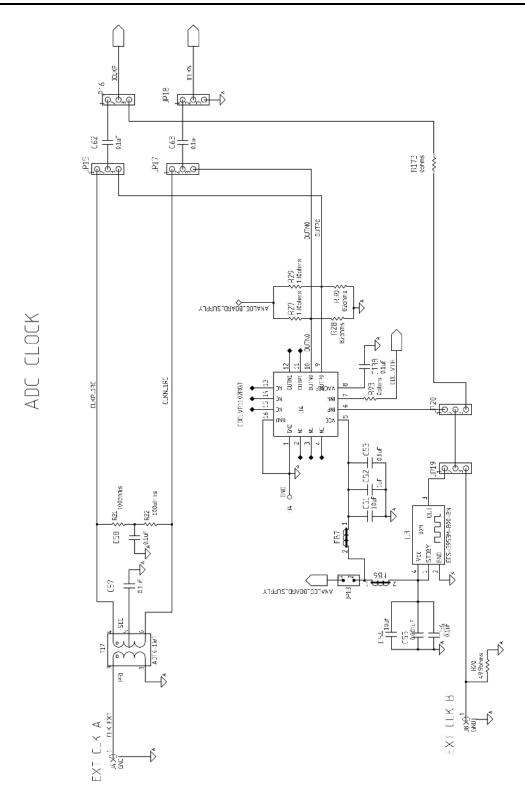


Figure 19. Schematic, Sheet 5 of 9



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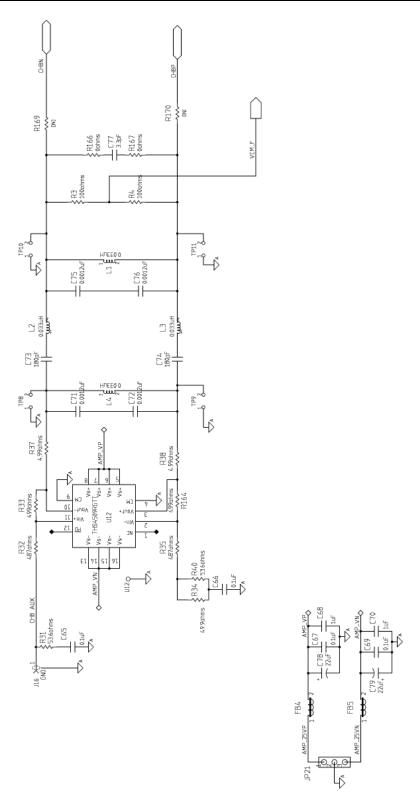


Figure 20. Schematic, Sheet 6 of 9



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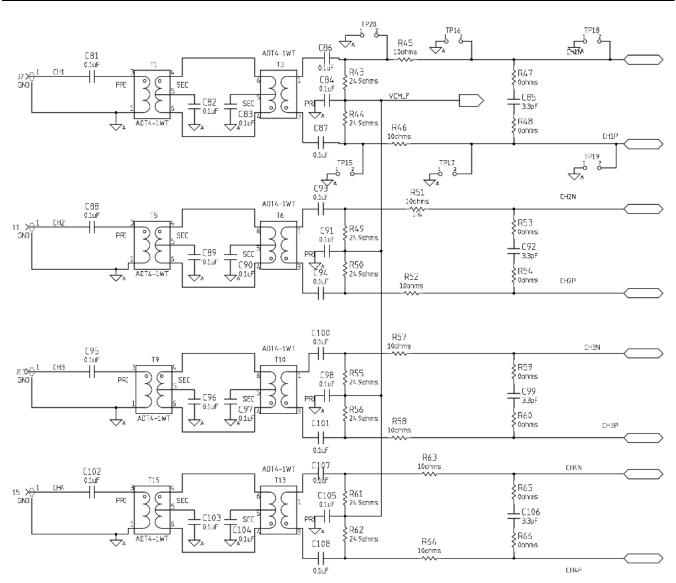


Figure 21. Schematic, Sheet 7 of 9



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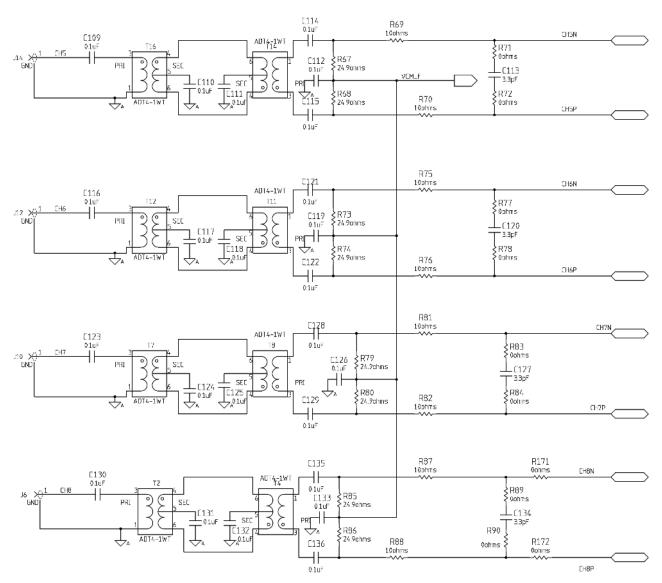


Figure 22. Schematic, Sheet 8 of 9



EVM Schematics www.ti.com

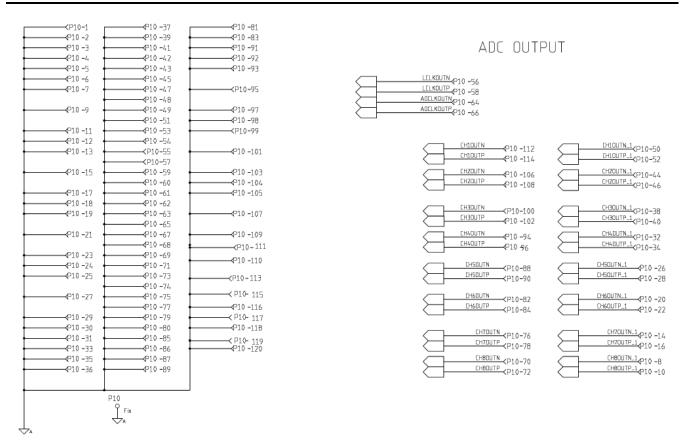


Figure 23. Schematic, Sheet 9 of 9



## 11 ADS5294EVM Bill of Materials

## **Bill of Materials**

| QTY | MFR P/N            | Description   | Value        | MFR                                   | REF DES  |
|-----|--------------------|---|--------------|---------------------------------------|--|
| 1   | ADS5294IPFP        | 14-Bit 8-Channel ADC                                | ADS5294      | Texas<br>Instruments                  | DUT1   |
| 17  | ADT4-1WT+          | RF TRANSFORMER WIDEBAND, 2-775 MHz, 50 $\Omega$     | ADT4-1WT+    | Mini-Circuits                         | T1-T17   |
| 1   | CDCLVP1102RGT      | TWO LVPECL OUTPUT CLOCK BUFFER                      | CDCLVP1102   | Texas<br>Instruments                  | U4   |
| 2   | CRCW06034R99FKEA   | RES 4.99 Ω, 1/10 W, 1% 0603 SMD                     | 4.99 Ω       | Vishay/Dale                           | R37, R38   |
| 16  | CRCW040210R0FKED   | RES 10 Ω, 1/16,W, 1% 0402 SMD                       | 10 Ω         | Vishay/Dale                           | R45, R46, R51, R52, R57, R58,<br>R63, R64, R69, R70, R75, R76,<br>R81, R82, R87, R88   |
| 1   | CRCW040249R9FKED   | RES 49.9 Ω, 1/16,W, 1% 0402 SMD                     | 49.9 Ω       | Vishay/Dale                           | R34  |
| 2   | CRCW060353R6FKEA   | RES 53.6 Ω 1/10W 1% 0603 SMD                        | 53.6 Ω       | Vishay/Dale                           | R31, R40   |
| 1   | CRCW06030000Z0EA   | RES 0 Ω 1/10W 0603 SMD                              | 0 Ω          | Vishay/Dale                           | R36  |
| 2   | CRCW0603487RFKEA   | RES 487 Ω 1/10W 1% 0603 SMD                         | 487 Ω        | Vishay/Dale                           | R32, R35   |
| 4   | CRCW0402100RFKED   | RES 100 Ω 1/16W 1% 0402 SMD                         | 100 Ω        | Vishay/Dale                           | R3, R4, R21, R22   |
| 3   | CRCW04021K00FKED   | RES 1K Ω 1/16W 1% 0402 SMD                          | 1 kΩ         | Vishay/Dale                           | R2, R12, R168  |
| 2   | CRCW0402499RFKED   | RES 499 Ω 1/16W 1% 0402 SMD                         | 499 Ω        | Vishay/Dale                           | R33, R164  |
| 3   | CRCW080510K0FKEA   | RES 10K Ω 1/8W 1% 0805 SMD                          | 10Κ Ω        | Vishay/Dale                           | R11, R13, R14  |
| 7   | C0402C104K8PACTU   | CAP 0.10UF 10V CERAMIC X5R 0402                     | 0.1 μF       | Kemet                                 | C36, C37, C40, C41, C44, C45, C48  |
| 1   | ECJ-0EB1H102K      | CAPACITOR, SMT, 0402, CER, 1000pF, 50V, 10%, X7R    | 1000 pF      | Panasonic                             | C55  |
| 4   | ECJ-0EB1H122K      | CAPACITOR, SMT, 0402, CER, 1200pF, 50V, 10%, X7R    | 1200 pF      | Panasonic                             | C71, C72, C75, C76   |
| 2   | ECJ-0EB1E181K      | CAP 180PF 25V CERAMIC X7R 0402                      | 180 pF       | Panasonic                             | C73, C74   |
| 2   | ECJ-0EC1H390J      | CAP 39PF 50V CERAMIC 0402 SMD                       | 39 PF        | Panasonic                             | C29, C30   |
| 5   | ECJ-1V41E105M      | CAP 1UF 25V CERAMIC 0603 X5S                        | 1 μF         | Panasonic - ECG                       | C26, C31, C52, C68, C70  |
| 1   | ECS-3953M-800-BN   | OSC, SMT, 3.3V, 50ppm, -40~85°C, 5nS, 80.000 MHz    | OSC 80 MHz   | ECS Inc                               | U3   |
| 4   | ELJ-RE33NGFA       | INDUCTOR 33NH 2% 0603 SMD                           | 33NH         | Panasonic                             | L1–L4  |
| 2   | ERJ-2GEJ131        | RESISTOR, SMT, 0402, THICK FILM, 5%, 1/16W, 130     | 130 Ω        | Panasonic                             | R27, R29   |
| 2   | ERJ-2GEJ820        | RESISTOR, SMT, 0402, THICK FILM, 5%, 1/16W, 82      | 82 Ω         | Panasonic                             | R28, R30   |
| 27  | ERJ-2GE0R00X       | RESISTOR/JUMPER, SMT, 0402, 0 $\Omega$ , 5%, 1/16W  | ΟΩ           | Panasonic                             | R5–R8, R10, R47, R48, R53,<br>R54, R59, R60, R65, R66, R71,<br>R72, R77, R78, R83, R84, R89,<br>R90, R93, R166, R167,<br>R171–R173 |
| 16  | ERJ-2RKF24R9X      | RESISTOR, SMT, 0402, 24.9 Ω, 1%, 1/16W              | 24.9 Ω       | Panasonic                             | R43, R44, R49, R50, R55, R56,<br>R61, R62, R67, R68, R73, R74,<br>R79, R80, R85, R86   |
| 2   | ERJ-2RKF49R9X      | RESISTOR, SMT, 0402, 49.9 Ω, 1%, 1/16W              | 49.9 Ω       | Panasonic                             | R1, R20  |
| 3   | ERJ-2RKF1000X      | RESISTOR, SMT, 0402, 100 Ω, 1%, 1/10W               | 100 Ω        | Panasonic                             | R15, R16, R18  |
| 1   | ERJ-2RKF3320X      | RESISTOR, SMT, 0402, 332 Ω, 1%, 1/16W               | 332 Ω        | Panasonic                             | R17  |
| 1   | FT245RL            | USB FIFO IC INCORPORATE FTDICHIP-ID SECURITY DONGLE | USB          | FTDI                                  | U10  |
| 9   | GRM1555C1H3R3CZ01D | CAP CER 3.3PF 50V C0G 0402                          | 3.3 pF       | Murata                                | C77, C85, C92, C99, C106, C113, C120, C127, C134   |
| 8   | HI0805R800R-10     | FERRITE CHIP POWER 80 Ω SMD                         | FERRITE      | Laird-Signal<br>Integrity<br>Products | FB1–FB8  |
| 2   | ISO7240MDW         | QUAD DIGITAL ISOLATORS                              | IC DGTL ISOL | Texas<br>Instruments                  | U9, U11  |
| 3   | JMK107BJ106MA-T    | CAPACITOR, SMT, 0603, CERAMIC, 10μF, 6.3V, 20%, X5R | 10 μF        | Taiyo Yuden                           | C33, C51, C54  |
| 10  | JUMPER-0603(UN)    | UNINSTALLED JUMPER, SMT0603                         | DNI          |                                       | TP8-TP11, TP15-TP20  |



# **Bill of Materials (continued)**

| QTY | MFR P/N              | Description  | Value                | MFR                     | REF DES  |
|-----|----------------------|--|----------------------|-------------------------|--|
| 3   | LNJ308G8PRA          | LED, SMT, 0603, PURE GREEN, 2.03V                                | LED                  | Panasonic               | LED18VA, LED18VD,<br>LED_+5V   |
| 1   | LNJ808R8ERA          | LED, SMT, 0603, ORANGE, 1.8V                                     | LED                  | Panasonic               | LED33VA  |
| 1   | 897-43-005-00-100001 | CONN RECEPT MINI-USB TYPE B SMT                                  | USB Mini B           | Mill-Max                | USB1   |
| 1   | QTH-060-01-L-D-A     | HEADER, SMT, 120P, 0.5mm, FEM, 2BANK, RECEPTACLE, 168/198H       | CONN                 | Samtec Inc              | P10  |
| 2   | TEST POINT YELLOW    | NOT INSTALLED  | DNI                  |                         | TP22, TP35   |
| 1   | THS4509QRGTRQ1       | WIDEBAND, LOW NOISE, LOW DISTORTION FULLY DIFF AMP, 1900 MHz     | IC OPAMP             | Texas<br>Instruments    | U12  |
| 9   | TPSC226K016R0375     | 10%, 16V, 22μF   | 22 μF                | AVX                     | C35, C38, C39, C4, C43, C46, C47, C78, C79   |
| 2   | TPS79618DCQR         | ULTRALOW-NOISE HI PSRR FAST RF 1-A LDO<br>LINEAR REGULATOR, 1.8V | LDO REG              | Texas<br>Instruments    | U6, U7   |
| 1   | TPS79633DCQR         | ULTRALOW-NOISE HI PSRR FAST RF 1-A LDO LINEAR                    | LDO REG              | Texas<br>Instruments    | U8   |
| 1   | 1SMB5921BT3G         | DIODE ZENER 6.8V 3W SMB  | DIODE Zener          | ON<br>Semiconductor     | Z1   |
| 5   | 9-146285-0-02        | CONN HEADR BRKWAY 0.100 02POS STR                                | CONN Header          | TE Connectivity         | JP10–JP14  |
| 10  | 9-146285-0-03        | CONN HEADR BRKWAY 0.100 03POS STR                                | CONN Header          | TE Connectivity         | JP4-JP6, JP15-JP21   |
| 12  | 901-144-8            | SMA COAX STRAIGHT PCB CURRENT P/N IS 901-144-8RFX                | SMA                  | Amphenol                | J4–J8, J10–J16   |
| 76  | 0402YD104KAT2A       | CAP CERM 0.1μF 10% 16V X5R 0402                                  | 0.1 μF               | AVX                     | C1–C8, C13 C14, C17, C25,<br>C27, C28, C32, C34, C53,<br>C56–C58, C6, C63, C65–C67,<br>C69, C81–C84, C86–C91,<br>C93–C98, C100–C105,<br>C107–C112, C114–C119,<br>121–C126, C128–C133,<br>C135–C138 |
| 1   | 5000                 | TESTPOINT, THU, MINIATURE, 0.1LS, 120TL, RED                     | Test Point,Red       | Keystone<br>Electronics | TP_VP  |
| 9   | 5001                 | TESTPOINT, THU, MINIATURE, 0.1LS, 120TL, BLACK                   | Test<br>Point,Black  | Keystone<br>Electronics | TP1-TP5, TP14, TP21, TP23, TP25  |
| 5   | 5002                 | TESTPOINT, THU, MINIATURE, 0.1LS, 120TL, WHITE                   | Test<br>Point,White  | Keystone<br>Electronics | TP6, TP_D0-TP_D2, TP_D7  |
| 1   | 5003                 | TESTPOINT, THU, MINIATURE, 0.1LS, 120TL, ORANGE                  | Test<br>Point,Orange | Keystone<br>Electronics | TP34   |
| 1   | 39357-0002           | HEADER, THRU, POWER, 2P, 3.5MM, EUROSTYLE                        | CONN<br>TERMINAL     | Molex Connector<br>Corp | P1   |
| 2   | RESISTOR (DNI)       | NOT INSTALLED  | DNI                  |                         | R169, R170   |
| 4   | 24436                | STANDOFF HEX M3 THR ALUM 18MM                                    | STANDOFF             | Keystone                | STANDOFF HEX M3 THR<br>ALUM 18MM   |
| 4   | 29311                | SCREW STEEL M3 THR 6MM   | SCREW                | Keystone                | SCREW STEEL M3 THR 6MM   |



## 12 ADS5294EVM Printed-Circuit Board Layout

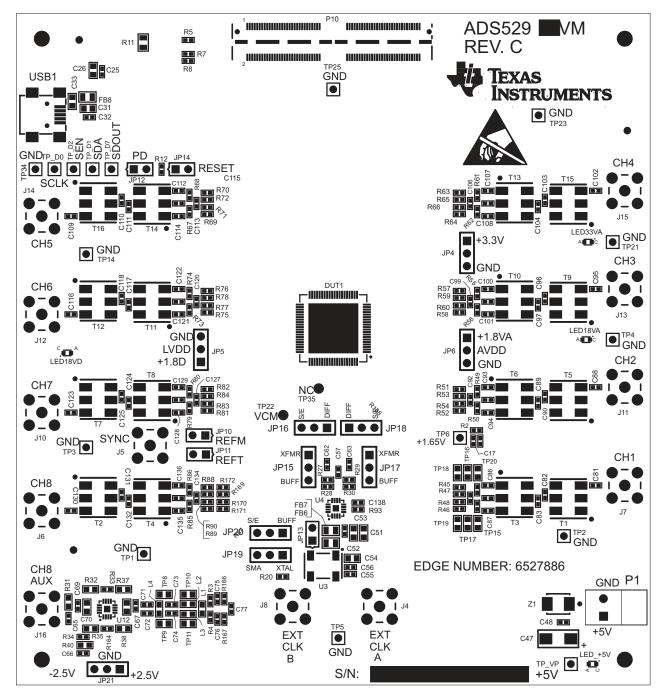


Figure 24. ADS5294EVM Top Layer Assembly Drawing - Top View



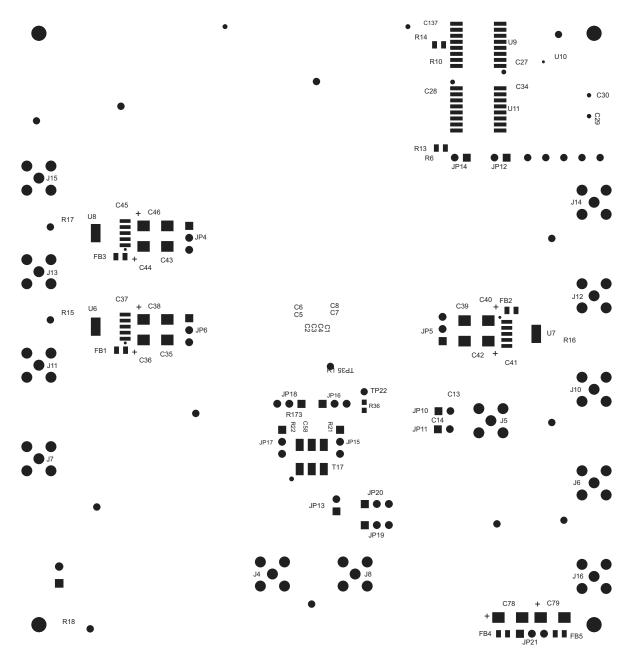


Figure 25. ADS5294EVM Bottom Layer Assembly Drawing - Bottom View



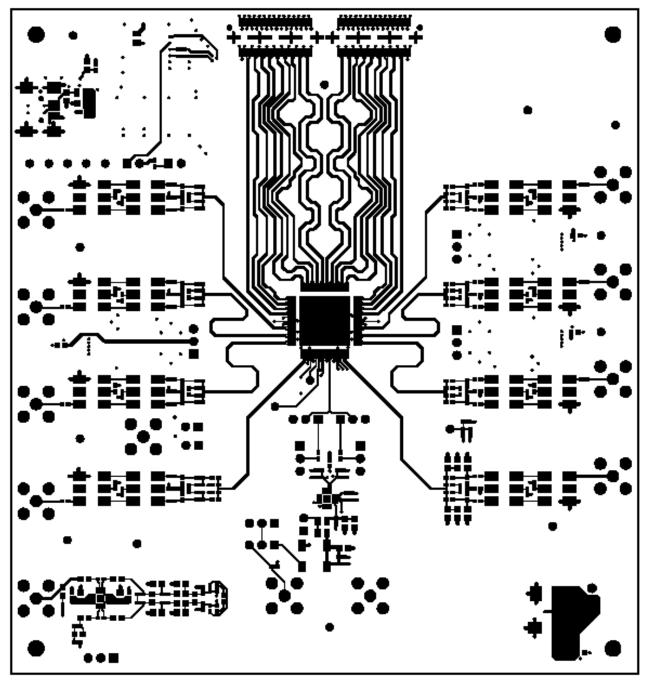


Figure 26. ADS5294EVM Top Layer Copper – Top View



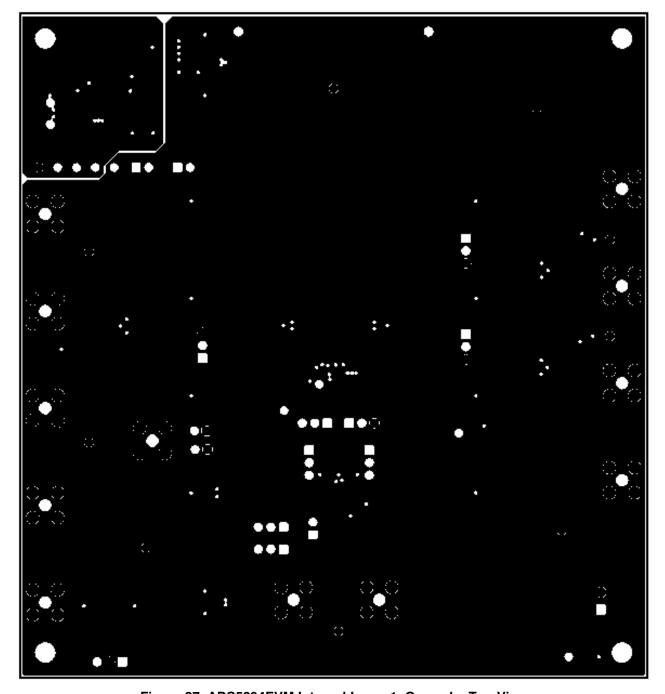


Figure 27. ADS5294EVM Internal Layer 1, Ground – Top View



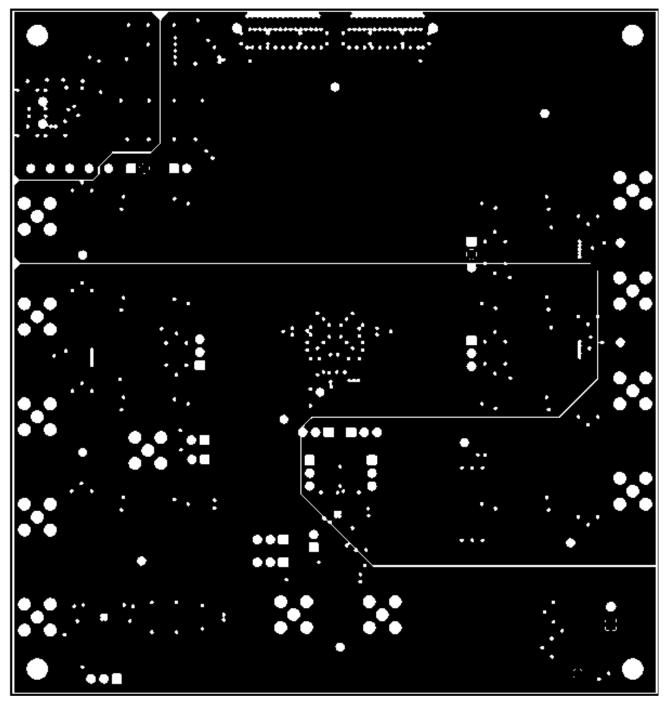


Figure 28. ADS5294EVM Internal Layer 2, Power - Top View



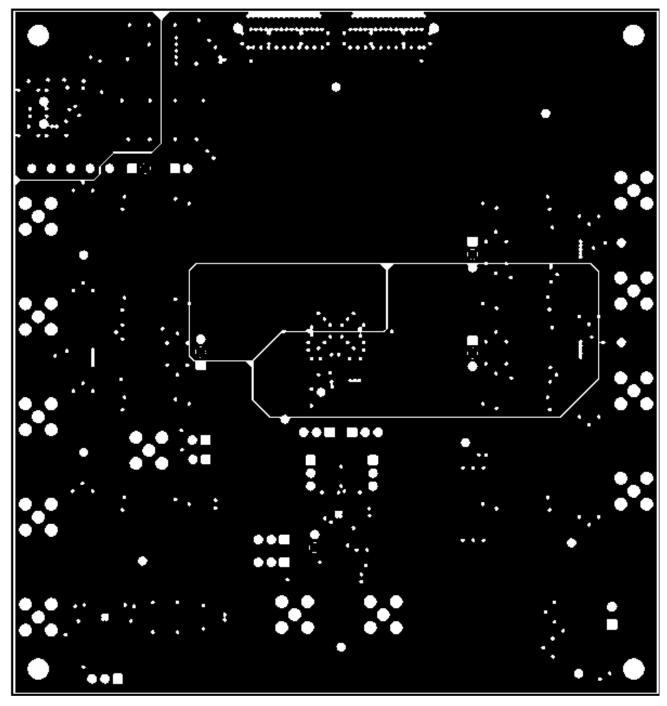


Figure 29. ADS5294EVM Internal Layer 3, Power - Top View



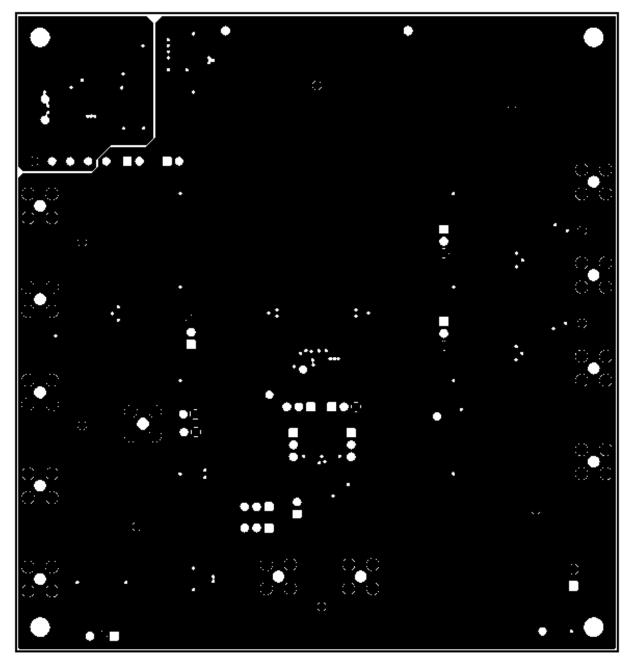


Figure 30. ADS5294EVM Internal Layer 4, Ground - Top View



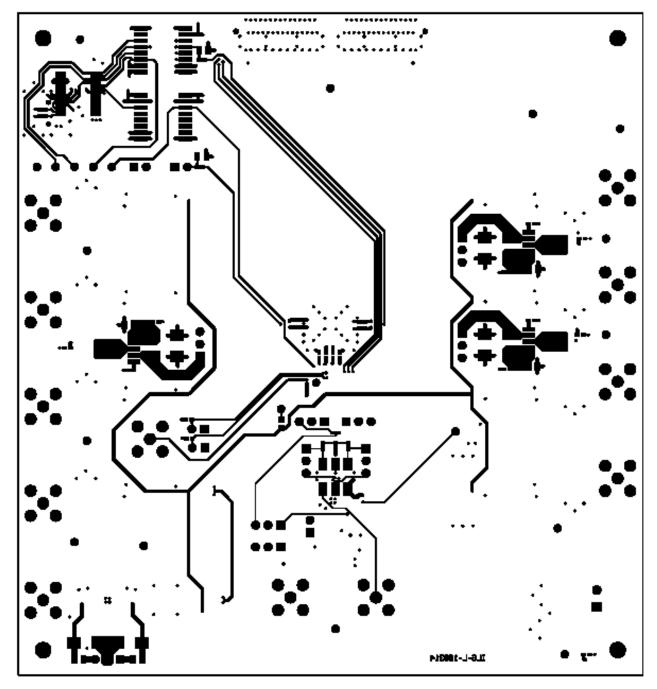


Figure 31. ADS5294EVM Bottom Layer Copper - Top View



# High Speed Data Converter Pro (HSDCPro) GUI Installation

Download the HSDCPro GUI Installer using this link: HSDCPro GUI

- Unzip the saved folder and run the installer executable to obtain the pop-up shown in Figure 32.
- Click the Install button.

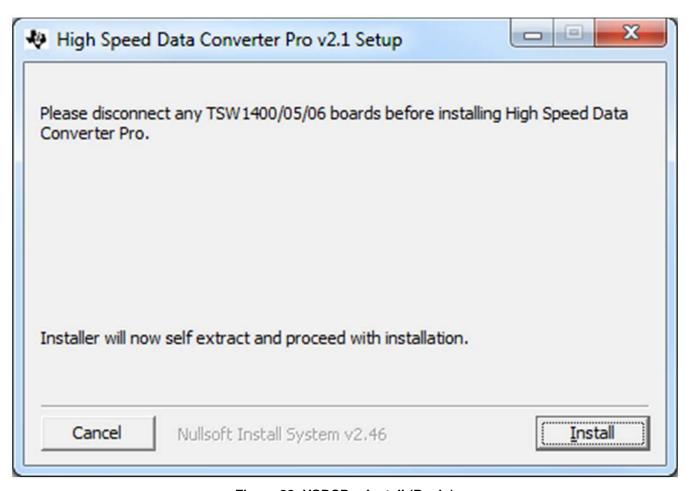


Figure 32. HSDCPro Install (Begin)

 Leave the destination directories as the default location, for the TSW1400GUI installation and press the NEXT button as shown in Figure 33.



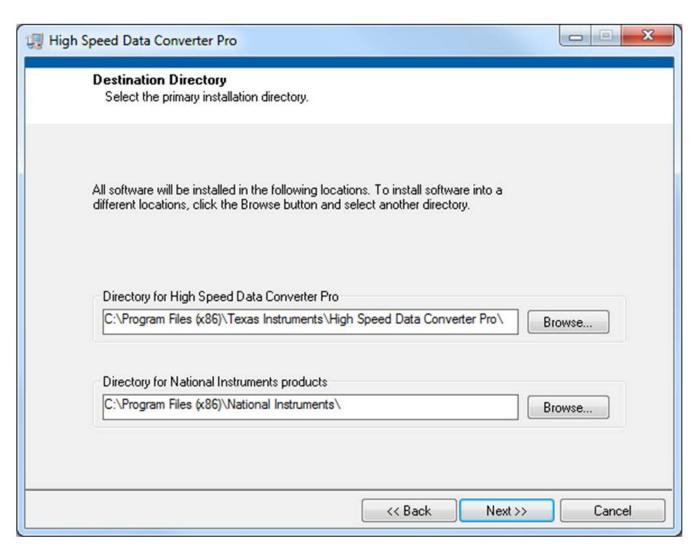


Figure 33. HSDCPro Install (Install Directory)

• Read the License Agreement from Texas Instruments and select *I accept the License Agreement* and press the *Next* button as shown in Figure 34.



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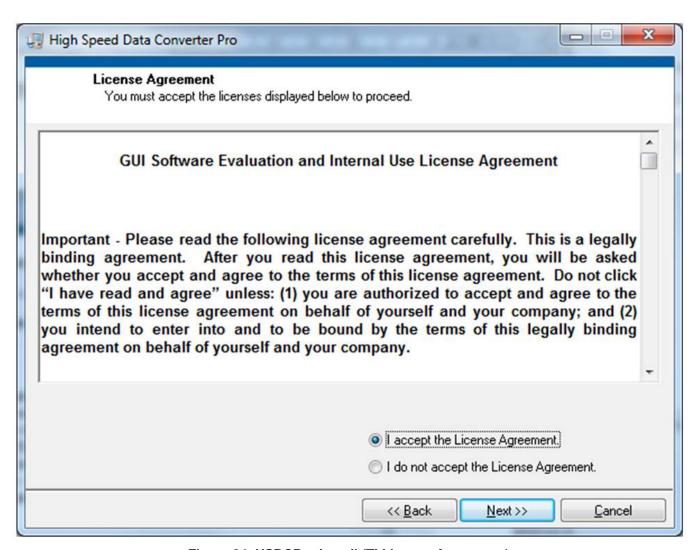


Figure 34. HSDCPro Install (TI License Agreement)

• Read the License Agreement from National Instruments and select *I accept the License Agreement* and press the *Next* button as shown in Figure 35.



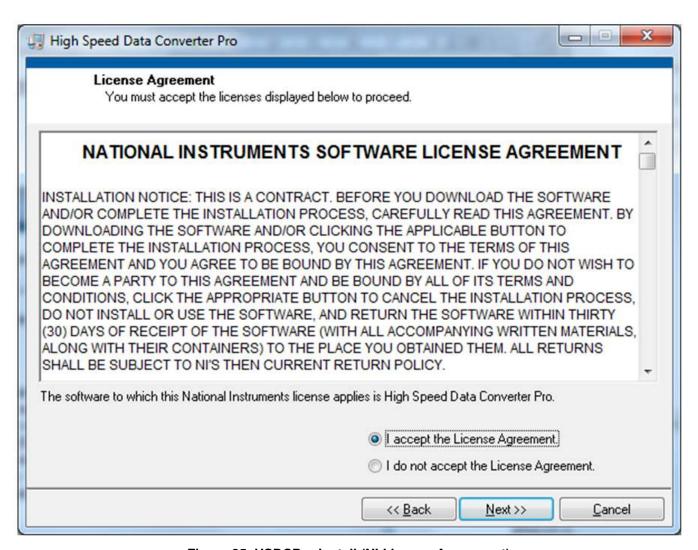


Figure 35. HSDCPro Install (NI License Agreement)

Press the Next button as shown in Figure 36.



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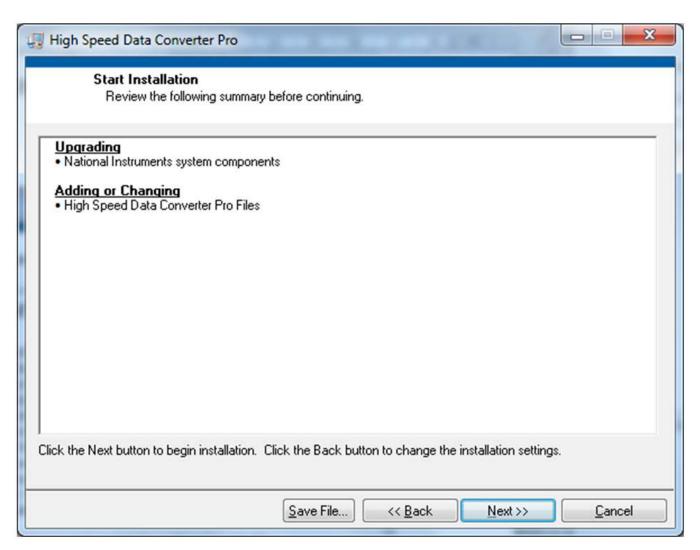


Figure 36. HSDCPro Install (Start Installation)

• The window shown in Figure 37 should appear indicating that the installation is in progress.



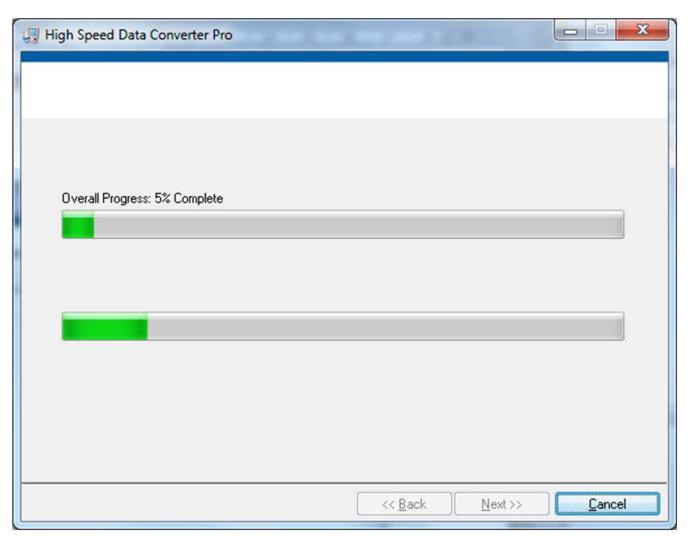


Figure 37. HSDCPro Install (Installation Progress)

• The window shown in Figure 38 appears indicating Installation Complete. Press the Next button.



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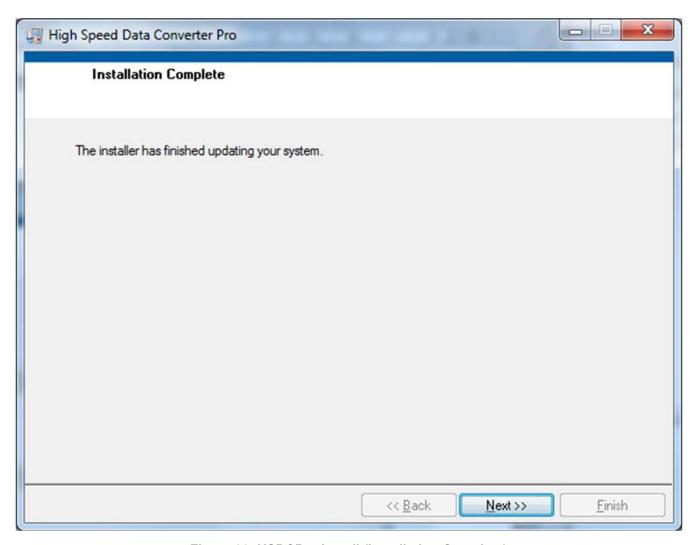


Figure 38. HSDCPro Install (Installation Complete)

• The window shown in Figure 39 appears briefly to complete the process.



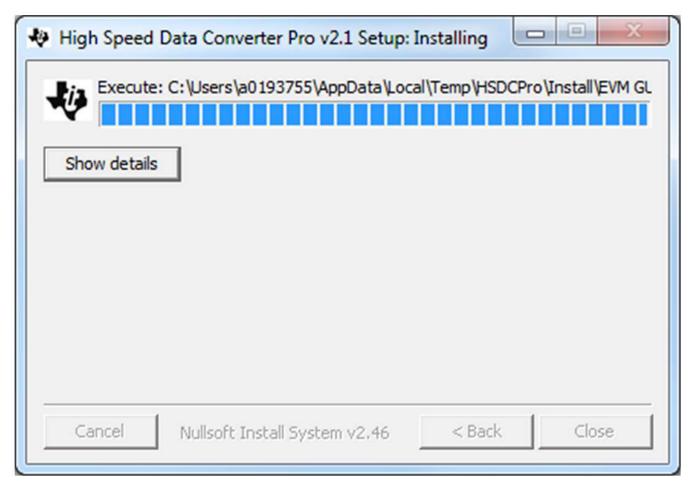


Figure 39. HSDCPro Install (h)

• As shown in Figure 40 a restart might be requested depending on whether or not the PC already had the National Instruments MCR Installer. If requested, hit the *Restart* button to complete the installation.

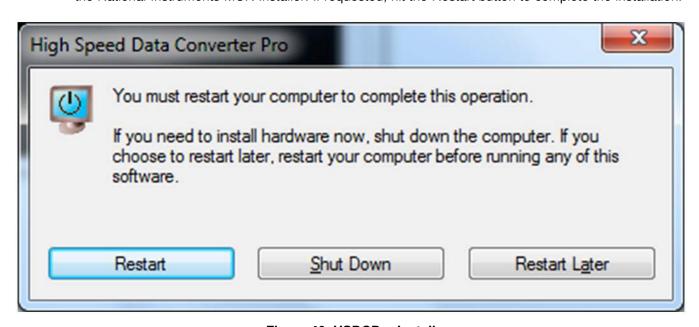


Figure 40. HSDCPro Install



www.ti.com Revision History

## **Revision History**

| Changes from Original (July 2011) to A Revision |   | Page |    |
|---|---|------|----|
| •   | Added Appendix A: High Speed Data Converter Pro (HSDCPro) GUI Installation. | 4    | 11 |
|   |   |      | _  |

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

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  - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
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  - 2.1 These terms and conditions do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
  - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for any defects that are caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI. Moreover, TI shall not be liable for any defects that result from User's design, specifications or instructions for such EVMs. Testing and other quality control techniques are used to the extent TI deems necessary or as mandated by government requirements. TI does not test all parameters of each EVM.
  - 2.3 If any EVM fails to conform to the warranty set forth above, Tl's sole liability shall be at its option to repair or replace such EVM, or credit User's account for such EVM. Tl's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by Tl and that are determined by Tl not to conform to such warranty. If Tl elects to repair or replace such EVM, Tl shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.
- 3 Regulatory Notices:
  - 3.1 United States
    - 3.1.1 Notice applicable to EVMs not FCC-Approved:

This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

3.1.2 For EVMs annotated as FCC - FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:

#### **CAUTION**

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

#### FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

#### FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- · Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- · Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

### 3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210

#### **Concerning EVMs Including Radio Transmitters:**

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

#### Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

#### **Concerning EVMs Including Detachable Antennas:**

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

### Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur

#### 3.3 Japan

- 3.3.1 Notice for EVMs delivered in Japan: Please see <a href="http://www.tij.co.jp/lsds/ti\_ja/general/eStore/notice\_01.page">http://www.tij.co.jp/lsds/ti\_ja/general/eStore/notice\_01.page</a> 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
  http://www.tij.co.jp/lsds/ti\_ja/general/eStore/notice\_01.page
- 3.3.2 Notice for Users of EVMs Considered "Radio Frequency Products" in Japan: EVMs entering Japan are NOT certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, User is required by Radio Law of Japan to follow the instructions below with respect to EVMs:

- 1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
- 2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
- 3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

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- 2. 実験局の免許を取得後ご使用いただく。
- 3. 技術基準適合証明を取得後ご使用いただく。
- なお、本製品は、上記の「ご使用にあたっての注意」を譲渡先、移転先に通知しない限り、譲渡、移転できないものとします。 上記を遵守頂けない場合は、電波法の罰則が適用される可能性があることをご留意ください。

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- 4 EVM Use Restrictions and Warnings:
  - 4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.
  - 4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.
  - 4.3 Safety-Related Warnings and Restrictions:
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